



WAH LEE INDUSTRIAL CORP.

華立企業股份有限公司

Material Pioneer, Technology Navigator



INVESTOR MEETING

法說簡報

August 2012

2012年8月

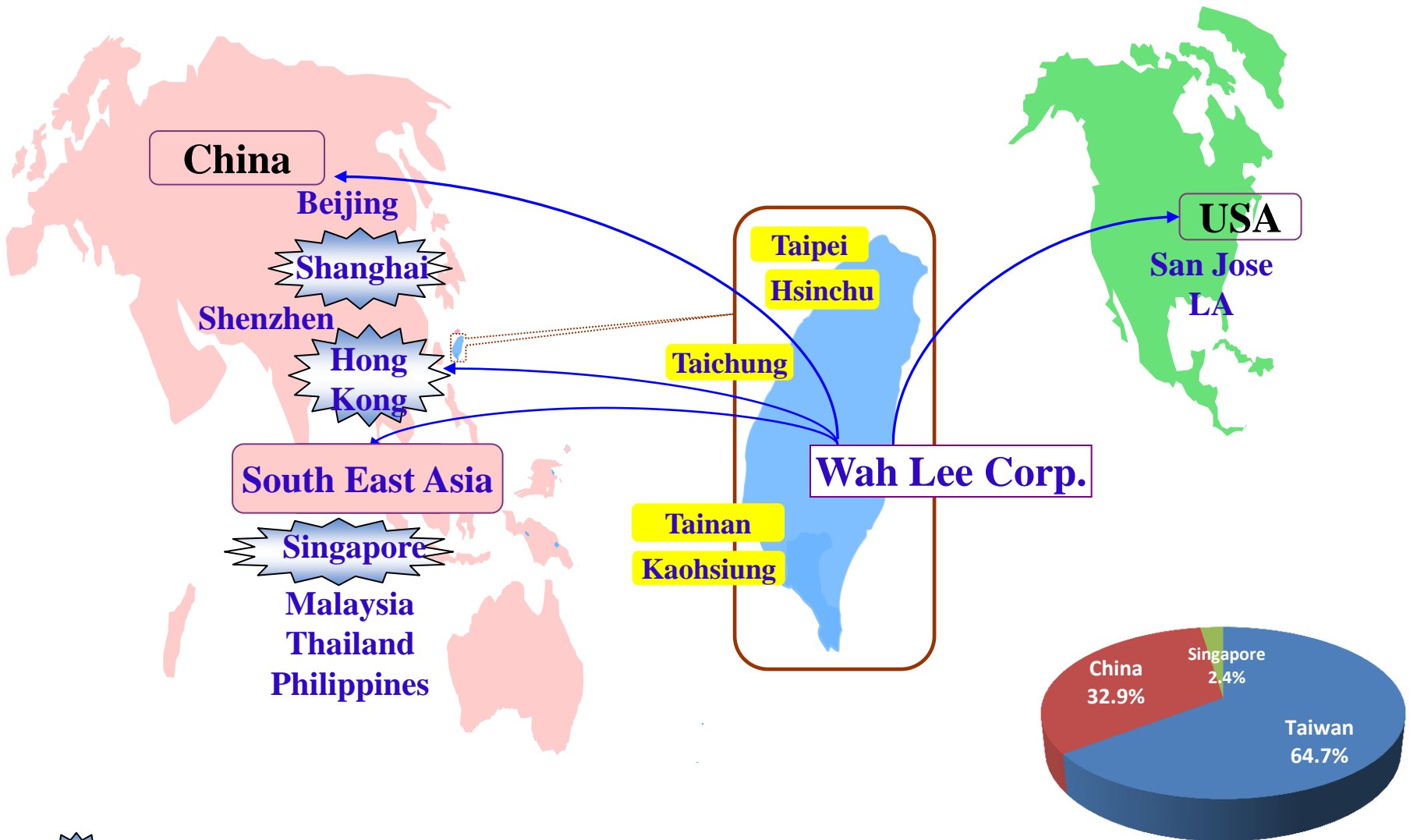
TSE Ticker : 3010 TT

<http://www.wahlee.com>

Company Profile 公司簡介

- Inception : 10/1/1968
成立日期
- Listing: 9/22/2002 on TSE(台灣證券交易所)
掛牌日期
- Capital: NT\$ 2,313,901,380
實收資本額
- Market Cap: ~USD\$300 million
市值
- Core Business: Leading HI-TECH solutions integrator and raw materials provider for :
主要業務
 - Computer / Communication
 - Semiconductor
 - PCB /Mother Board
 - FPD
 - Green Energy/Optoelectronics

Sales Offices 國際行銷據點

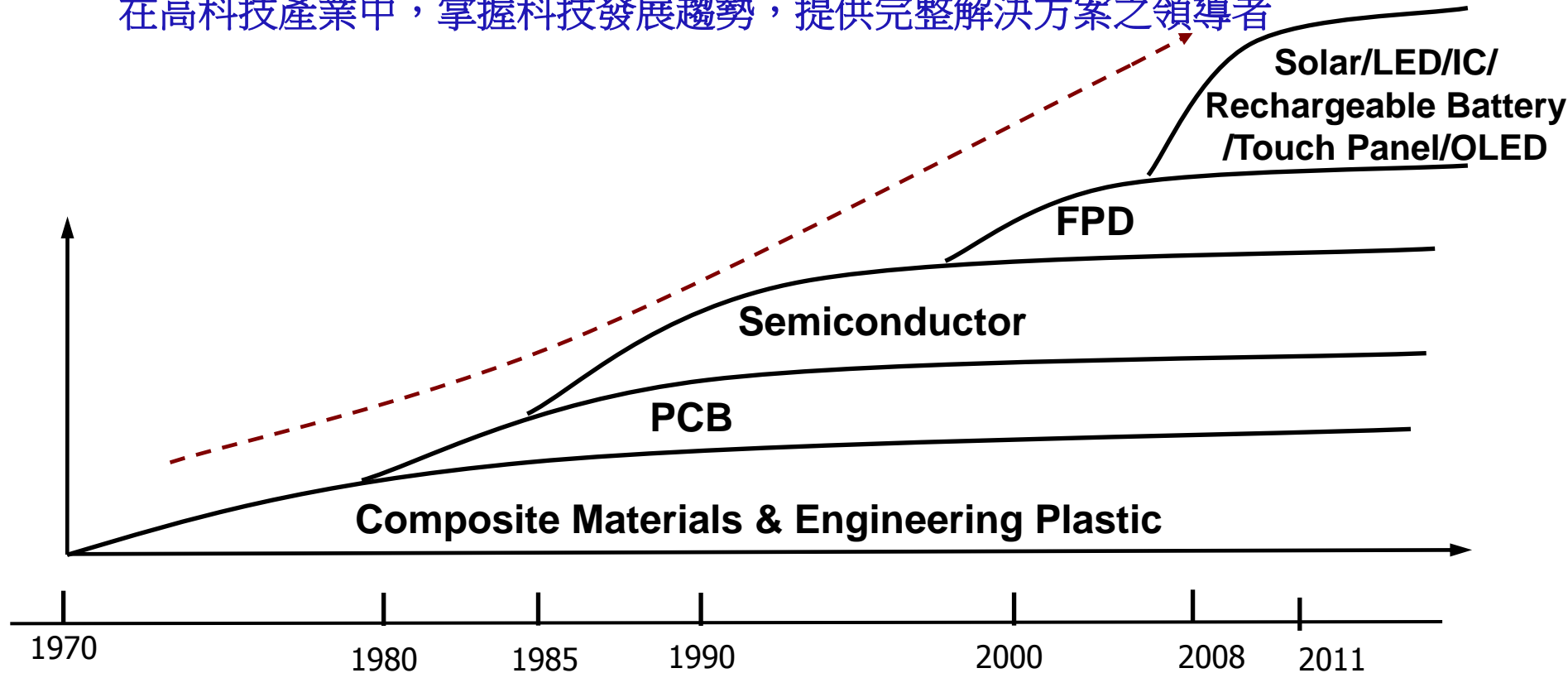


Wah Lee Subsidiaries

Wah Lee's Core Competence 華立核心競爭力

- I. Leader in foreseeing technology developments and solutions provider of upstream raw materials & equipment in high-tech industries

在高科技產業中，掌握科技發展趨勢，提供完整解決方案之領導者



- II. Developing Next Generation Technologies:

投資開發下一代明星產業，如先進顯示技術，固態照明，太陽能發電，電動車等

- **Advanced displays (3D, flexible, transparent...)**
- **Solid state lighting, advanced solar, electrical vehicle related systems...**

Wah Lee's Value Proposition 華立附加價值

Customers Buying Direct

客戶與供應商直接交易

Suppliers
供應商

Customers
客戶



Customers Buying through Wah Lee

華立在供應鏈中提供關鍵附加價值: 一次購足

Suppliers 供應商

Customers 客戶

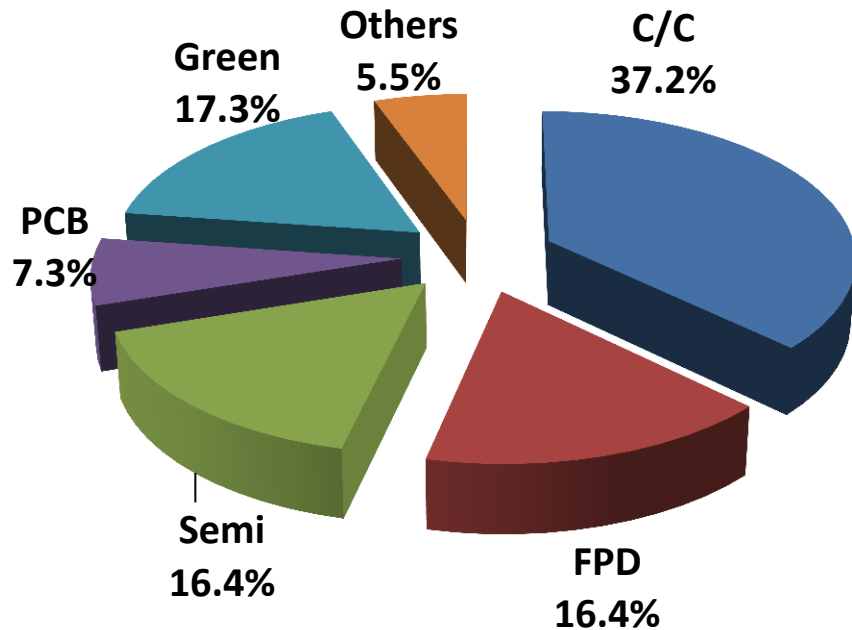


Industry Sales Breakdown

營收產業別資訊

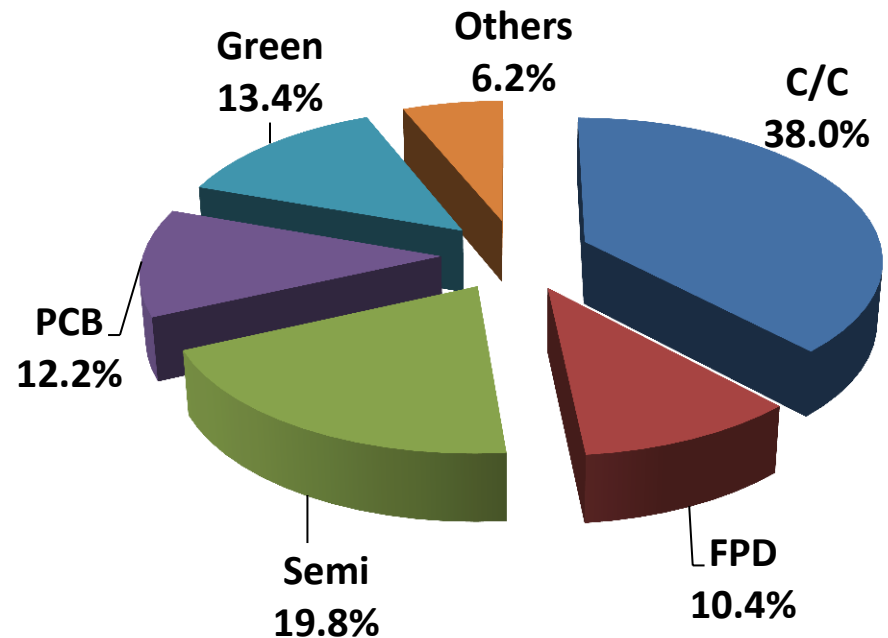
2012/ 01-07

Sales NT\$18.6 Billion

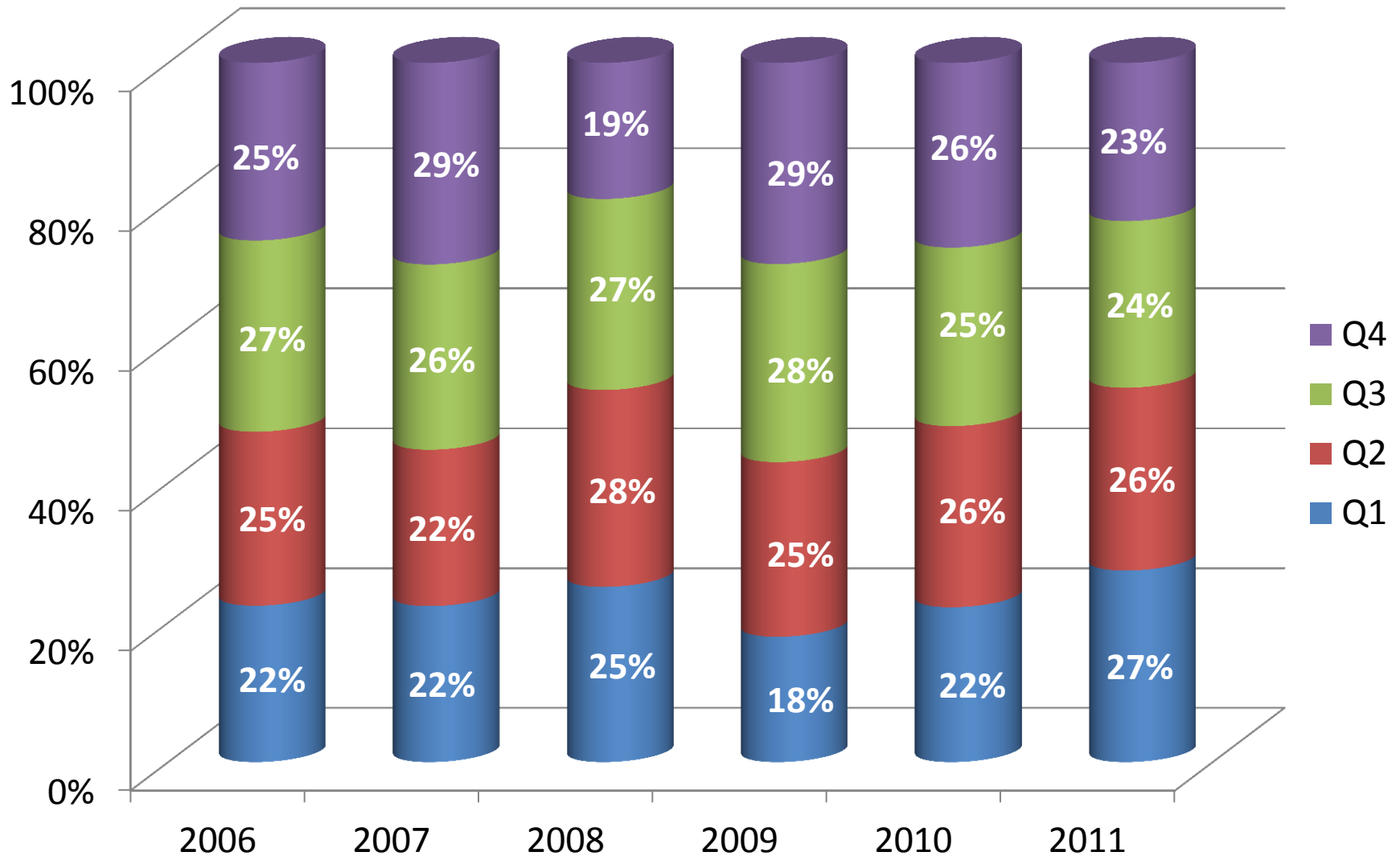


2011/ 01-07

Sales NT\$19.3 Billion



Quarterly Sales Percentage 歷年來各季營收比例



Consolidated Income 合併損益

Unit: NT\$ million	2012Q2 (CPA)	2012Q1 (CPA)	QoQ	2011Q2 (CPA)	YoY
Net Sales 營收淨額	8,279.3	7,734.1	7%	8,209.8	1%
Gross Profit 銷貨毛利	754.9	684.2	10%	833.0	-9%
Gross Margin 毛利率	9.1%	8.7%	0.4%	10.2%	-1.1%
Op. Expense 營業費用	527.0	451.6	17%	486.9	8%
Op. Profit 營業利益	227.9	232.6	-2%	346.1	-34%
Non-op. Profit 業外收支	93.2	74.9	24%	140.8	-34%
L-T investment income 長投收益	93.9	81.3	15%	94.1	0%
Disposal gain 處分利益	0.0	4.0	-100%	16.7	-100%
Others 其他	(0.7)	(10.4)	93%	30.1	-102%
Pre-tax Profit 稅前利潤	321.0	307.5	4%	486.9	-34%
Net Income 稅後淨利	220.7	241.2	-9%	334.3	-34%
After tax EPS	0.96	1.04	-9%	1.45	-34%

* Consolidated entities include: Wah Lee Taiwan and China Subsidiaries (Raycong, Shanghai YiKang), Wah Lee Japan, Wah Lee Tech(Singapore), and Wah Lee Korea.

*上述合併報表主體，包含華立台灣、大陸子公司(華港香港、上海怡康)，華立日本，華立新加坡，及華立韓國。

Long Term Investments 長期投資分析

Unit: NT\$ thousand

Long-term Investments 轉投資事業	Product Lines 主要產品線	Holding % 持有比例 %	2012 Q2 Earnings Recognized 長投收益	2012 H1 Earnings Recognized 長投收益
Chang Wah Electromaterials Inc. 長華電材	Semiconductor Packaging and Testing Materials	30	35,799	69,375
Nagase Wah Lee Plastics 長華塑膠	SABIC Engineering Plastics	40	39,445	62,520
Wah Hong Industrial Corp. 華宏新技	Optical Film, High Performance Plastic Compound, Heat Dissipation Solution, VCM Actuator	24	15,922	36,485
ORC Wah Lee Technology Corp. 華展光電	ORC Exposure Machine and Lamps	35	2,692	6,767
Total			93,858	175,147

Consolidated Balance Sheet 合併資產負債表

Unit: NT\$ million

	2012-6-30 (CPA)		2011-6-30 (CPA)			2012-6-30 (CPA)		2011-6-30 (CPA)	
Cash & Equiv. 現金	3,251	16.3%	1,972	10.1%	S-T Borrowing 短期借款	3,518	17.7%	4,001	20.4%
A/R 應收帳款	8,721	43.8%	8,887	45.4%	A/P 應付帳款	4,751	23.8%	4,750	24.2%
Inventory 存貨	2,592	13.0%	3,845	19.6%	Other C/L 其他流動負債	1,433	7.2%	1,555	7.9%
Other C/A					Current Liab. 流動負債	9,703	48.7%	10,307	52.6%
其他流動資產	552	2.8%	556	2.8%	L-T Liab. 長期負債	1,565	7.9%	1,033	5.3%
Current Assets 流動資產	15,116	75.8%	15,259	77.9%	Other Liab. 其他負債	640	3.2%	566	2.9%
L-T investments 長期投資	3,567	17.9%	3,098	15.8%	Total Liab. 總負債	11,917	59.8%	11,906	60.8%
Fixed Assets 固定資產	871	4.4%	881	4.5%	Capital 股本	2,314	11.6%	2,314	11.8%
Other Assets 其他資產	377	1.9%	354	1.8%	Capital Surplus 資本公積	1,268	6.4%	1,445	7.4%
					Retained Earnings 保留盈餘	3,852	19.3%	3,668	18.7%
					Minority int. & Other Adjust. 少數股權	580	2.9%	259	1.3%
Total Assets 總資產	19,930	100.0%	19,592	100.0%	Total Equities 總股東權益	8,014	40.2%	7,686	39.2%

* Consolidated entities include: Wah Lee Taiwan and China Subsidiaries (Raycong, Shanghai YiKang), Wah Lee Japan, Wah Lee Tech(Singapore), and Wah Lee Korea.

*上述合併報表主體，包含華立台灣、大陸子公司(華港香港、上海怡康)，華立日本，華立新加坡，及華立韓國。

Consolidated Financial Indicators 合併財務比率

	2007	2008	2009	2010	2011	2012Q2
Current Ratio 流動比率	144.8%	148.6%	171.7%	162.6%	164.4%	155.8%
Quick Ratio 速動比率	98.8%	95.6%	132.4%	115.9%	122.2%	125.4%
Net Debt/Equity 淨負債比率	36.2%	42.3%	9.0%	22.3%	31.0%	23.0%
A/R days 應收帳款天數	84.8	86.3	112.7	87.9	88.9	97.4
Inventory days 存貨天數	53.4	64.8	67.1	47.1	46.2	36.2
A/P days 應付帳款天數	57.9	54.2	81.5	60.8	56.8	60.3
Cash conversion days 現金週轉天數	80.3	96.9	98.3	74.1	78.2	73.3
Operating cash flow (NT\$K) 來自營業活動現金流量	243,444	636,700	2,539,747	-389,836	603,187	697,926
ROE 股東權益報酬率	18.7%	11.9%	12.3%	19.7%	12.0%	11.7%

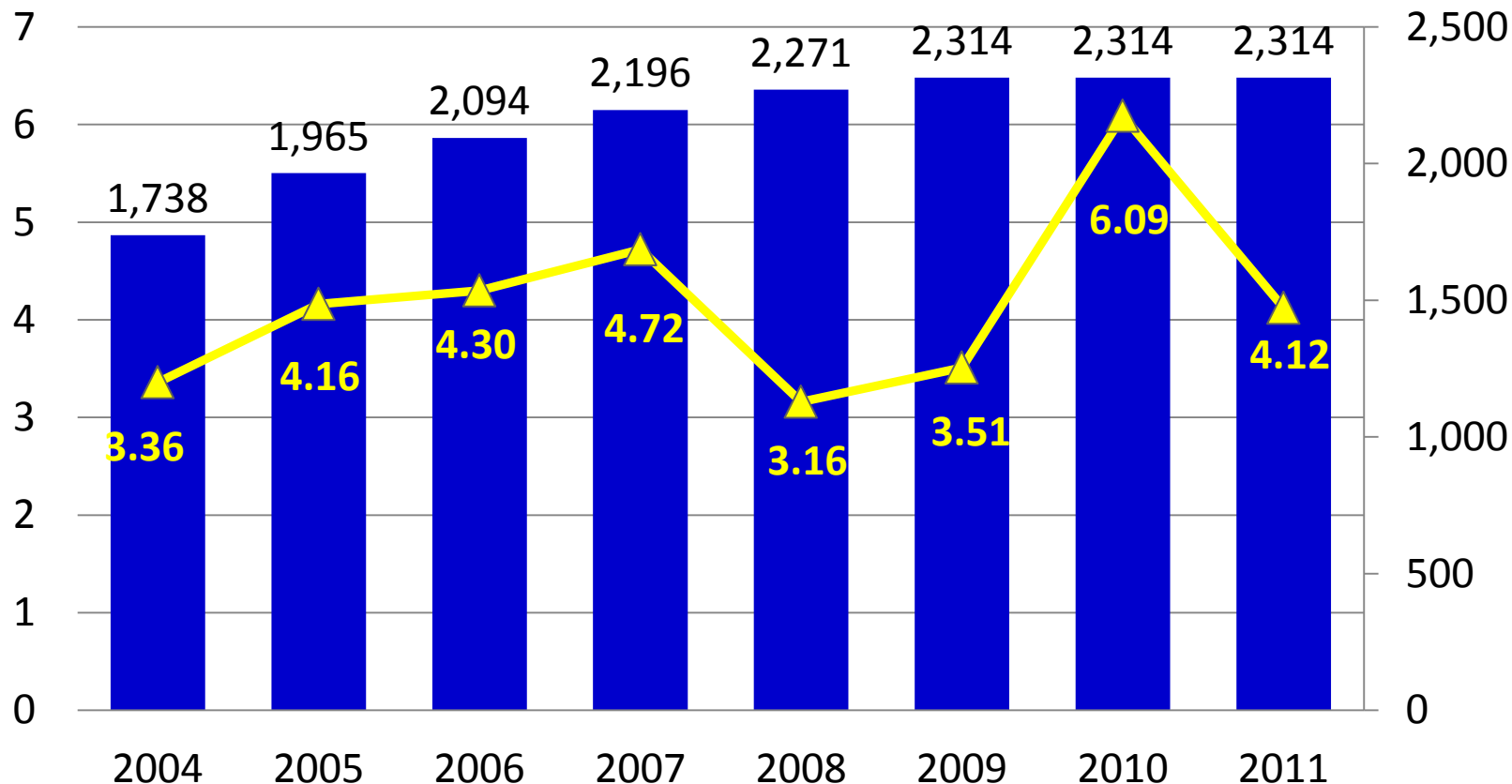
*2012 年第二季的股東報酬率已呈現為年化報酬率
ROE of 2012Q2 is annualized.

After Tax EPS vs Capital Trend

稅後每股盈餘 vs. 資本額

EPS NT \$
每股盈餘

Capital 資本額
NT\$ Million

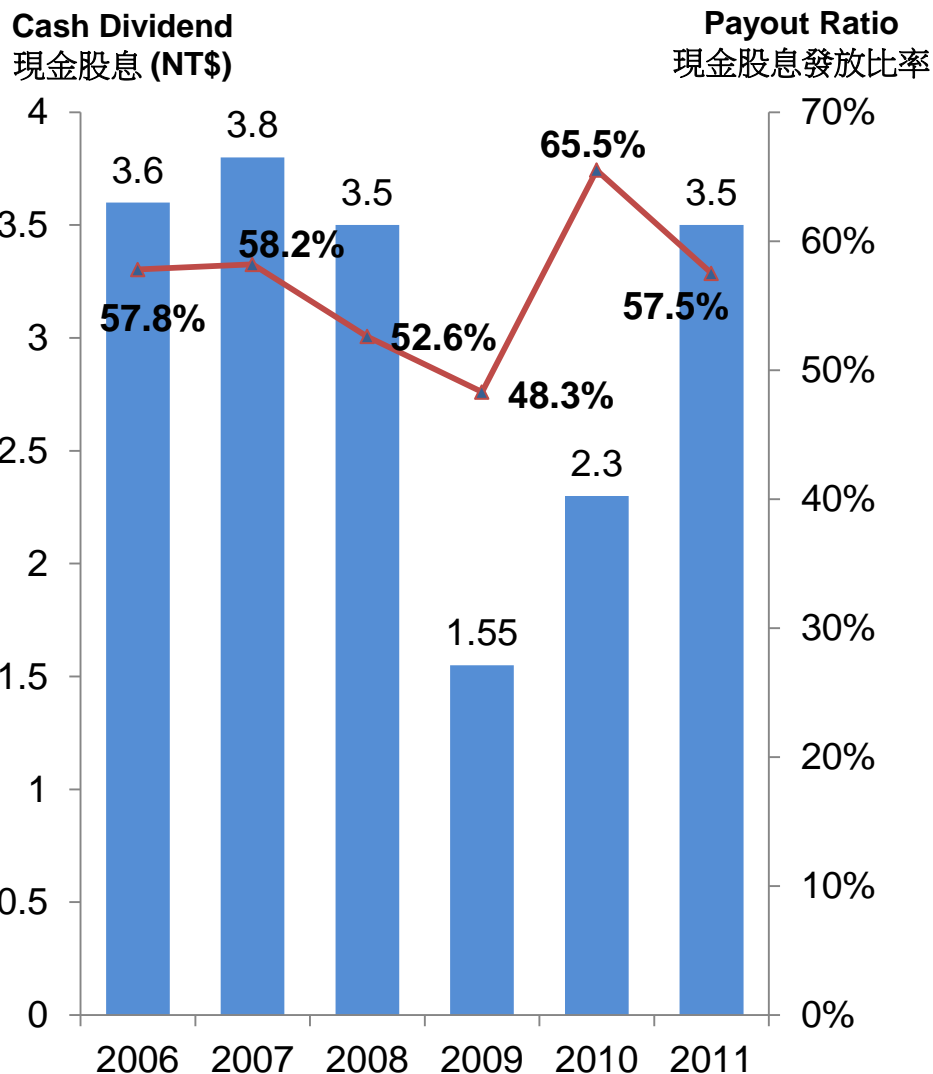


* All EPS prior to 2007 are all deducted by Employee Bonus Expenses to be comparable across the board.

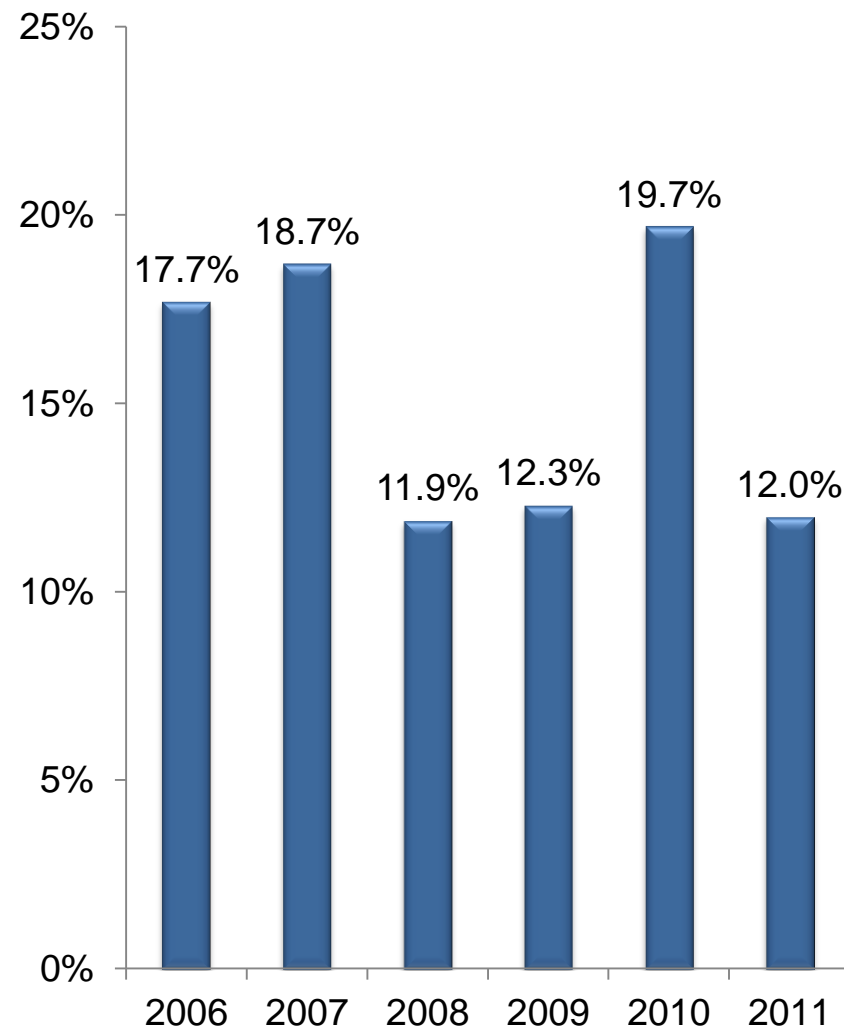
* 2007年及之前各年EPS已經過員工分紅費用之追溯調整，各年EPS具一致之比較基準。

Shareholder Returns Trend 股東投資報酬

Dividend Policy 股利政策



ROE 股東權益報酬率



* Dividends are distribution of prior year earnings.

Appendix 附錄

2011 Consolidated Income 合併損益

Unit: NT\$ million	2011 (CPA)	2010 (CPA)	YoY Growth
Net Sales 營收淨額	31,225	27,023	15.5%
Gross Profit 銷貨毛利	2,822	3,200	-11.8%
Gross Margin 毛利率	9.04%	11.84%	-2.8%
Op. Expense 營業費用	1,882	2,028	-7.2%
Op. Profit 營業利益	940	1,172	-19.9%
Non-op. Profit 業外收支	410	640	-35.9%
L-T investment income 長投收益	264	471	-43.8%
Disposal gain 處分利益	37	100	-62.5%
Others 其他	108	70	55.1%
Pre-tax Profit 稅前利潤	1,350	1,812	-25.5%
Net Income 稅後淨利	952	1,410	-32.5%
After tax EPS	4.12	6.09	-32.3%

* Consolidated entities include: Wah Lee Taiwan and China Subsidiaries (Raycong, Shanghai YiKang), Wah Lee Japan, Wah Lee Tech(Singapore), and Wah Lee Korea.

*上述合併報表主體，包含華立台灣、大陸子公司(華港香港、上海怡康)，華立日本，華立新加坡，及華立韓國。

2011 Long Term Investments

2011 長期投資分析

Unit: NT\$ thousand

Long-term Investments 轉投資事業	Product Lines 主要產品線	Holding % 持有比例 %	2011 Earnings Recognized 長投收益
Chang Wah Electromaterials Inc. 長華電材	Semiconductor Packaging and Testing Materials	30	14,671
Nagase Wah Lee Plastics 長華塑膠	SABIC Engineering Plastics	40	161,234
Wah Hong Industrial Corp. 華宏新技	Optical Film, High Performance Plastic Compound, Heat Dissipation Solution, VCM Actuator	24	80,243
ORC Wah Lee Technology Corp. 華展光電	ORC Exposure Machine and Lamps	35	8,182
Total			264,330

Additional dividend income from cost-method investment 成本法股息收益: **14,454**

2011 Consolidated Balance Sheet

2011 合併資產負債表

Unit: NT\$ million

	2011-12-31 (CPA)		2010-12-31 (CPA)			2011-12-31 (CPA)		2010-12-31 (CPA)	
Cash & Equiv. 現金	2,471	13.1%	2,039	11.7%	S-T Borrowing 短期借款	3,354	17.8%	2,733	15.6%
A/R 應收帳款	7,793	41.3%	7,303	41.8%	A/P 應付帳款	4,384	23.2%	4,513	25.8%
Inventory 存貨	3,229	17.1%	3,425	19.6%	Other C/L 其他流動負債	831	4.4%	860	4.9%
Other C/A					Current Liab. 流動負債	8,568	45.4%	8,106	46.3%
其他流動資產	596	3.2%	499	2.9%	L-T Liab. 長期負債	1,569	8.3%	1,041	6.0%
Current Assets 流動資產	14,088	74.6%	13,266	75.8%	Other Liab. 其他負債	644	3.4%	529	3.0%
L-T investments 長期投資	3,486	18.5%	2,957	16.9%	Total Liab. 總負債	10,781	57.1%	9,676	55.3%
Fixed Assets 固定資產	898	4.8%	903	5.2%	Capital 股本	2,314	12.2%	2,314	13.2%
Other Assets 其他資產	418	2.2%	365	2.1%	Capital Surplus 資本公積	1,268	6.7%	1,319	7.5%
					Retained Earnings 保留盈餘	3,922	20.8%	3,780	21.6%
					Minority int. & Other Adjust. 少數股權	499	2.6%	402	2.3%
Total Assets 總資產	18,890	100.0%	17,491	100.0%	Total Equities 總股東權益	8,109	42.9%	7,814	44.7%

* Consolidated entities include: Wah Lee Taiwan and China Subsidiaries (Raycong, Shanghai YiKang), Wah Lee Japan, Wah Lee Tech(Singapore), and Wah Lee Korea.

*上述合併報表主體，包含華立台灣、大陸子公司(華港香港、上海怡康)，華立日本，華立新加坡，及華立韓國。

Products in C/C 資訊通訊產品

I. High Performance Engineering Plastics

1. Case : Carbon Fiber 、TORAY CFRP 、PA

2. Lens : OKP4 、ARTON 、HARD COATED

SHEET

3. Insulating Strip 、 Battery Label :
PET FILM 、 PC FILM 、 PBT FILM

4. Speaker : PET FILM

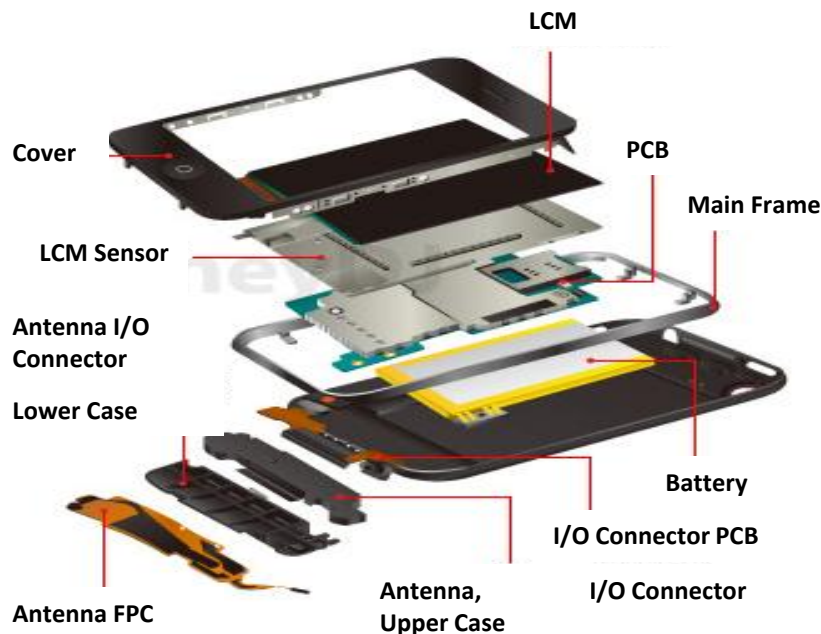
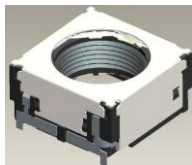
5. Charge Station : Phenolic Moulding
Compound

6. Connector : LCP 、 PA9T

7. Reflector : PA9T

8. Transformer /PFC: Phenolic
Moulding Compound

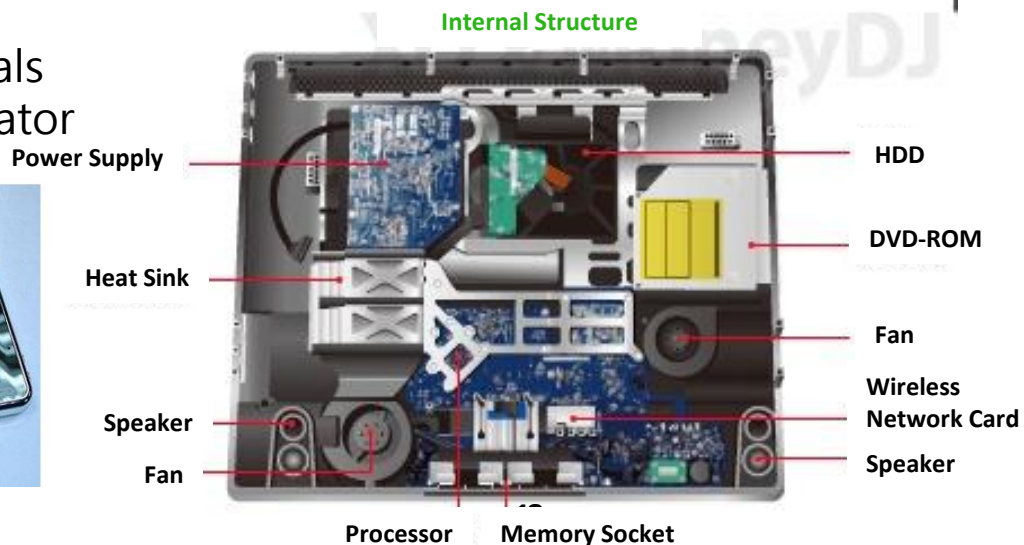
9. Inverter Bobbin : LCP



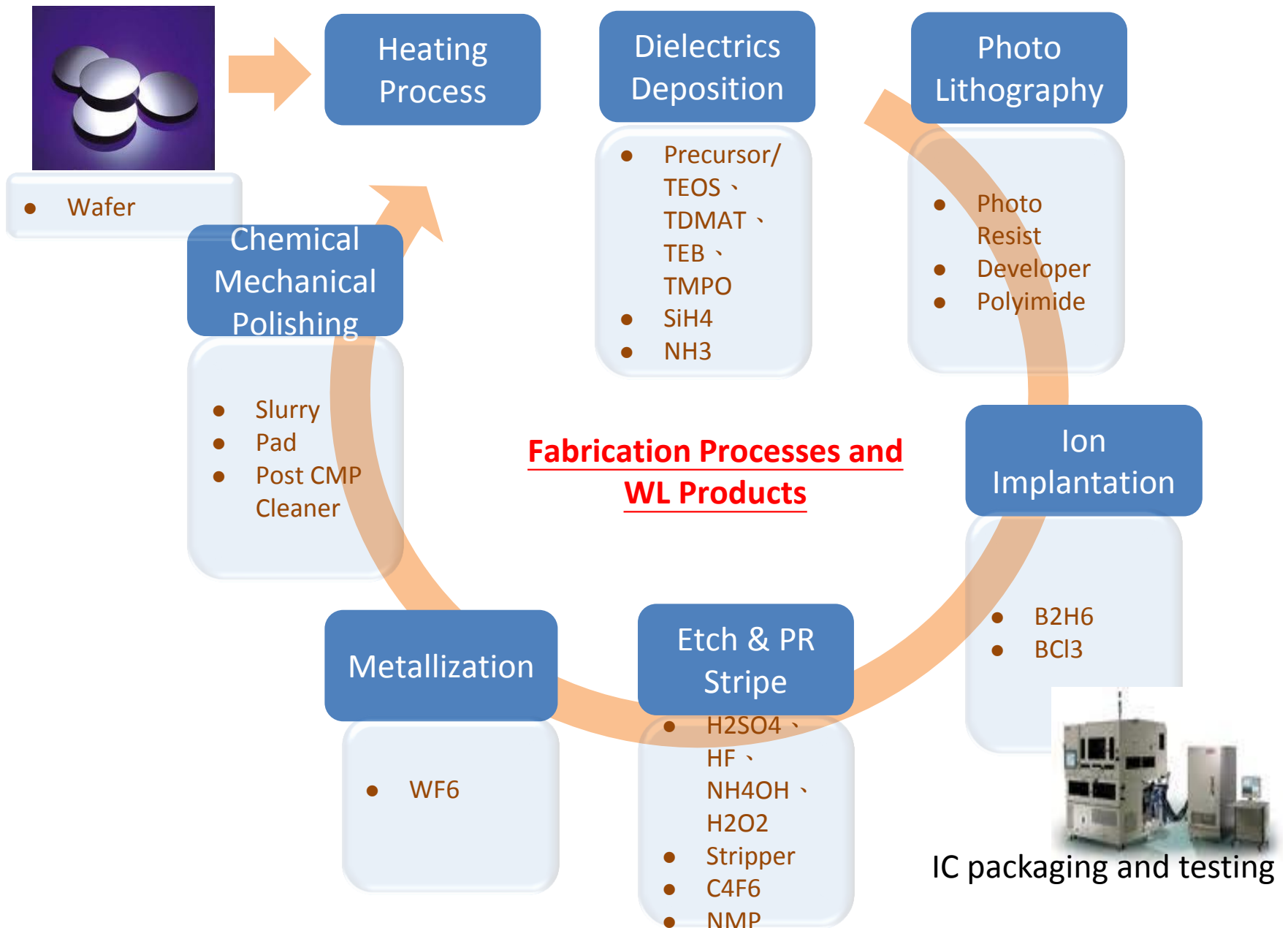
II. Others

1. Hik@xy Thermal Interface Materials

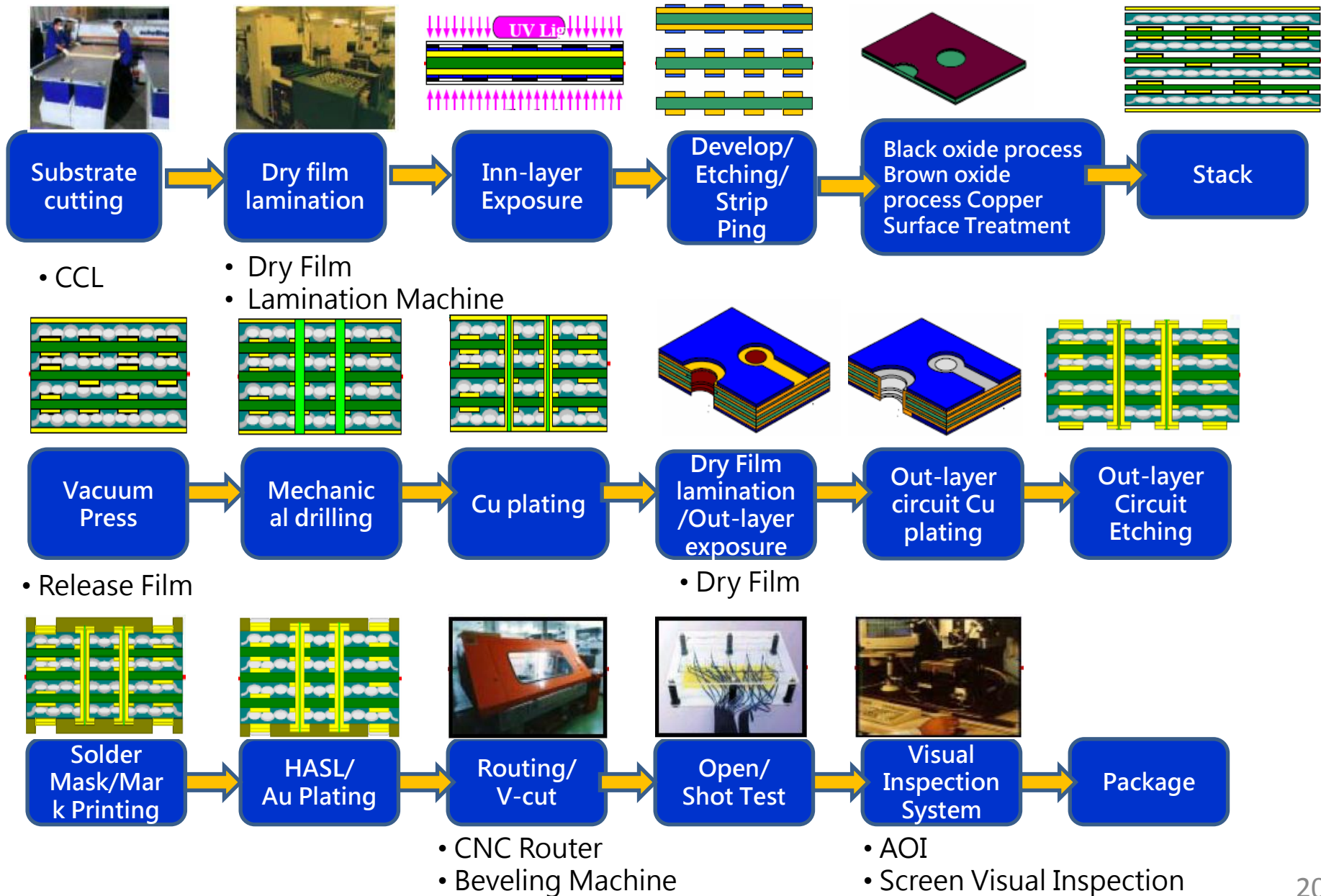
2. Camera Module Auto-focus Actuator



Products in Semiconductor Industry 半導體產品



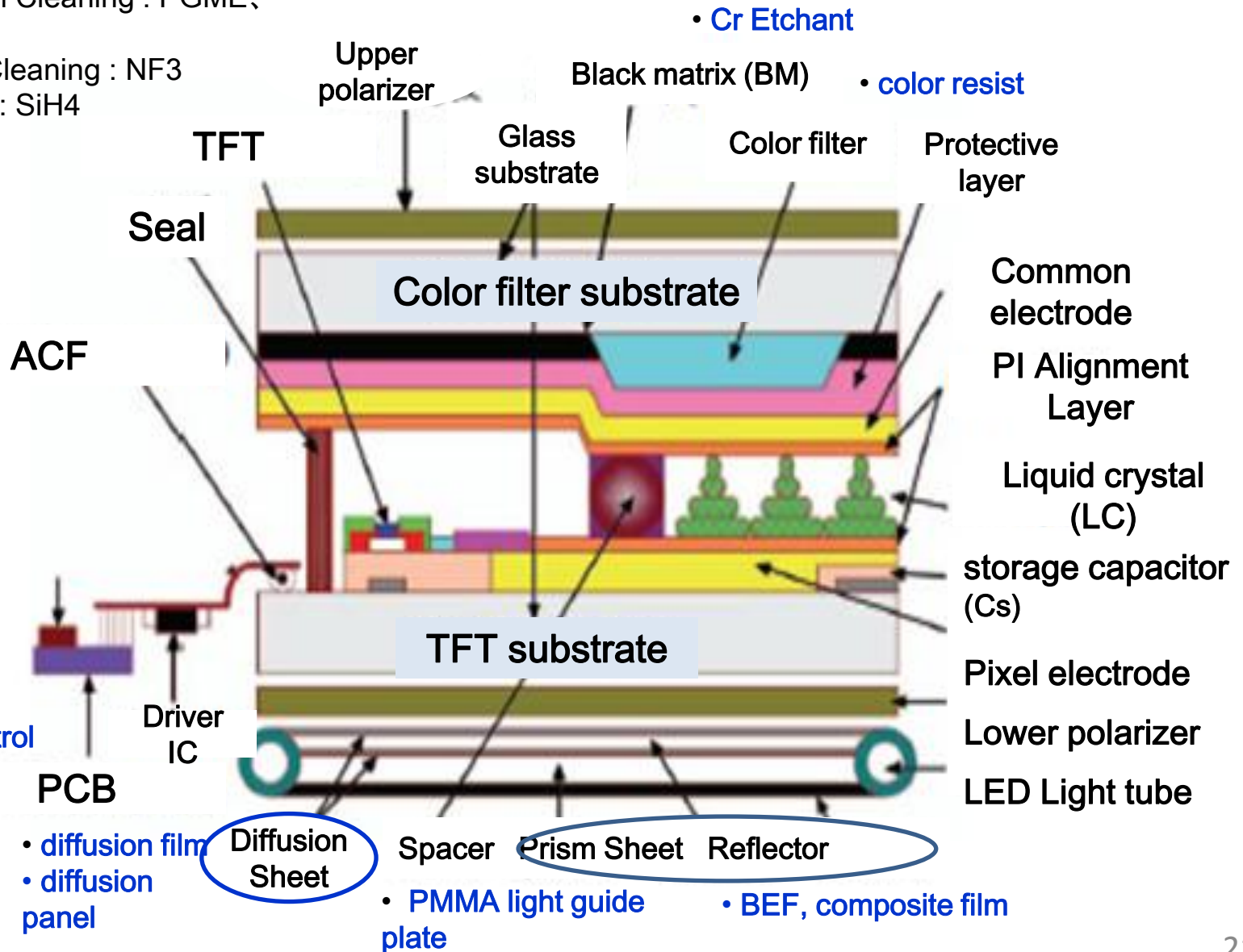
Products in PCB Industry PCB產業產品



Products in TFT LCD TFT LCD產品

Other chemicals and gas

1. Edge Beam Cleaning : PGME, PGMEA
2. Chamber Cleaning : NF3
3. Si thin-film : SiH4

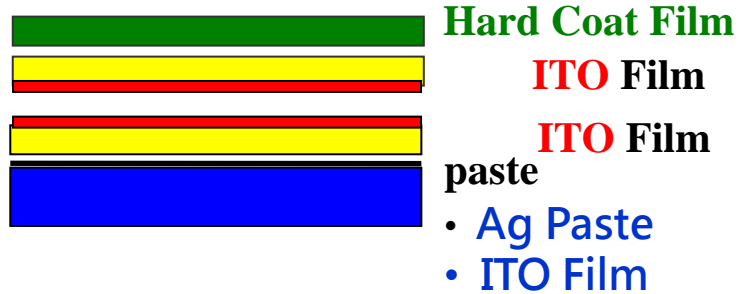


Products in Touch Panel Industry 觸控產品

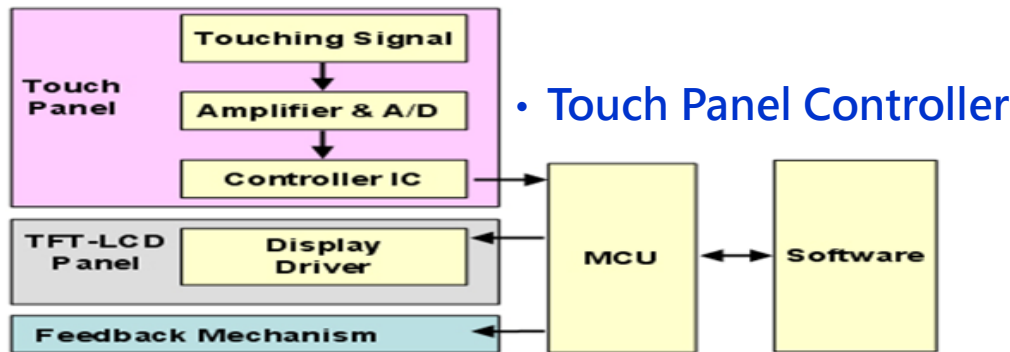
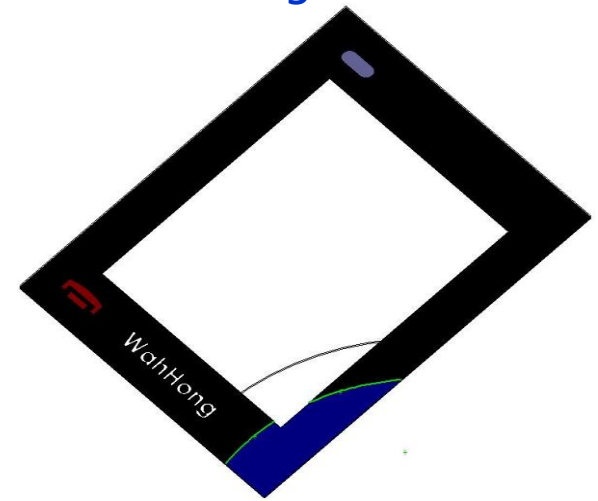


Conductive Silver Paste
Insulating Paste
Printing Ink

Vertical Structure

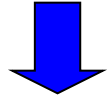


- Composite Plate/
Protective Film
- Hard Coated Film/Sheet
- I-con sheet/
Anti-scattering Film

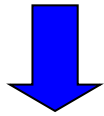


Products in LED Industry LED 產品

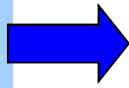
1. raw materials synthesizing



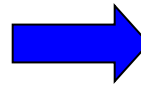
2. distilling/reductive
→ poly-crystalline



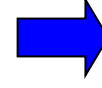
3. single crystal
→ ingot



4. wafer/ substrate



5. epitaxy



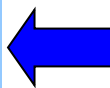
6. epitaxy wafer processing
(electrode patterning process)



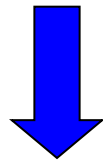
7. saw slicing to be chip



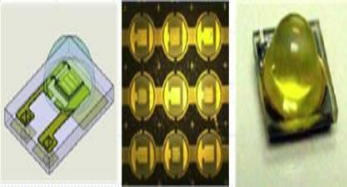
8. packaging



9. component/
module



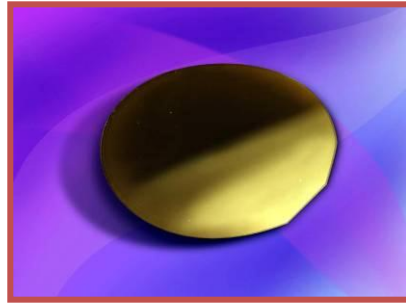
10. products/semi-
manufactured goods



- Emitter
- AC-LED
- Heat spreader
- Optical Film



- Street Lamps
- Lighting Equipments



saw slicing to be wafer,
and surface polishing

n pole
area



Ni/Au transparent conducting layer

p-GaN epitaxial layer, p =Mg

InGaN/GaN
MQW active layer

n-GaN epitaxial layer, n=Si

GaN nucleation layer (30nm)

Sapphire substrate (Al₂O₃)

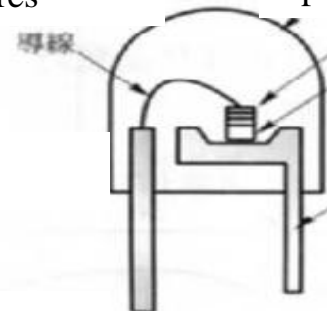
Ti/Al/Ti/Au p pole
welded pad

Ti/Al/Ti/Au n pole
welded pad

- NH₃
- TMGa (Tri Methyl Ga)
- TMIIn (Tri Methyl Indium)
- TMAI (Tri Methyl Al)
- DuPont Source (DCpMg, Si₂H₆)

connecting
wires

Epoxy



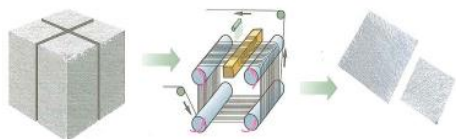
LED
conductive
paste
Lead frame



- PA9T
- LCP
- Phosphor
- LED Base Injection Machine
- Packaging Materials
- Die Bonding Silver Paste

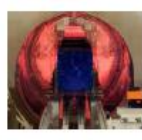
Products in Solar Industry 太陽能產品

- Wire saw
- Diamond saw
- Slurry recycling system



• Chamber Cleaning : NF3

Solar Cell



Wafer inspection

Etching & Cleaning

Phospho-rous Diffusion

Edge/back Isolation

AR Coating

Metali-zation

Firing

I-V curve testing/ sorting

- mono/poly silicon wafer
- quasi-mono wafer

- Etchant
- HCL · HNO3
- KOH · HF

• POCL3

- NH3
- SiH4 · DEZ
- 2%B2H6/H2

- Screen
- Al/Ag Paste

PV Module



Cell Selection

Welding

Module (with EVA, glass, Tedlar...)

Module Package

Al frame, wiring and assembling

Efficiency Test

- EVA Sheet
- Back Sheet
- Glass

- Conductive Paste

- PPE for Junction Box

Products in Rechargeable Battery 二次電池產品

